

ABSTRACT

A circuit board manufacturing method includes formation of a thermosetting photosensitive resin film on an insulating board by a spin coat method and the like, exposure of the photosensitive resin film to radiation rays such as ultraviolet rays, development with a developer or by etching, heat-hardening of the photosensitive resin film, oxygen plasma treatment or ultraviolet treatment if required, adjustment of a water quantity in the photosensitive resin film by drying the resin film, exposure in a fluorine gas atmosphere, anneal treatment, and then immersion of the resin film in a fluorinated acid chemical.